



SOT725-1

plastic DIL-bent-SIL power package; 37 leads (lead length 6.8 mm)

8 February 2016

Package information

1. Package summary

Terminal position code	Z (zig-zag)
Package type descriptive code	DBS37P
Package type industry code	DBS37P
Package style descriptive code	DBS (DIL-bent-SIL)
Package style suffix code	P (power)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	22-11-2002

Table 1. Package summary

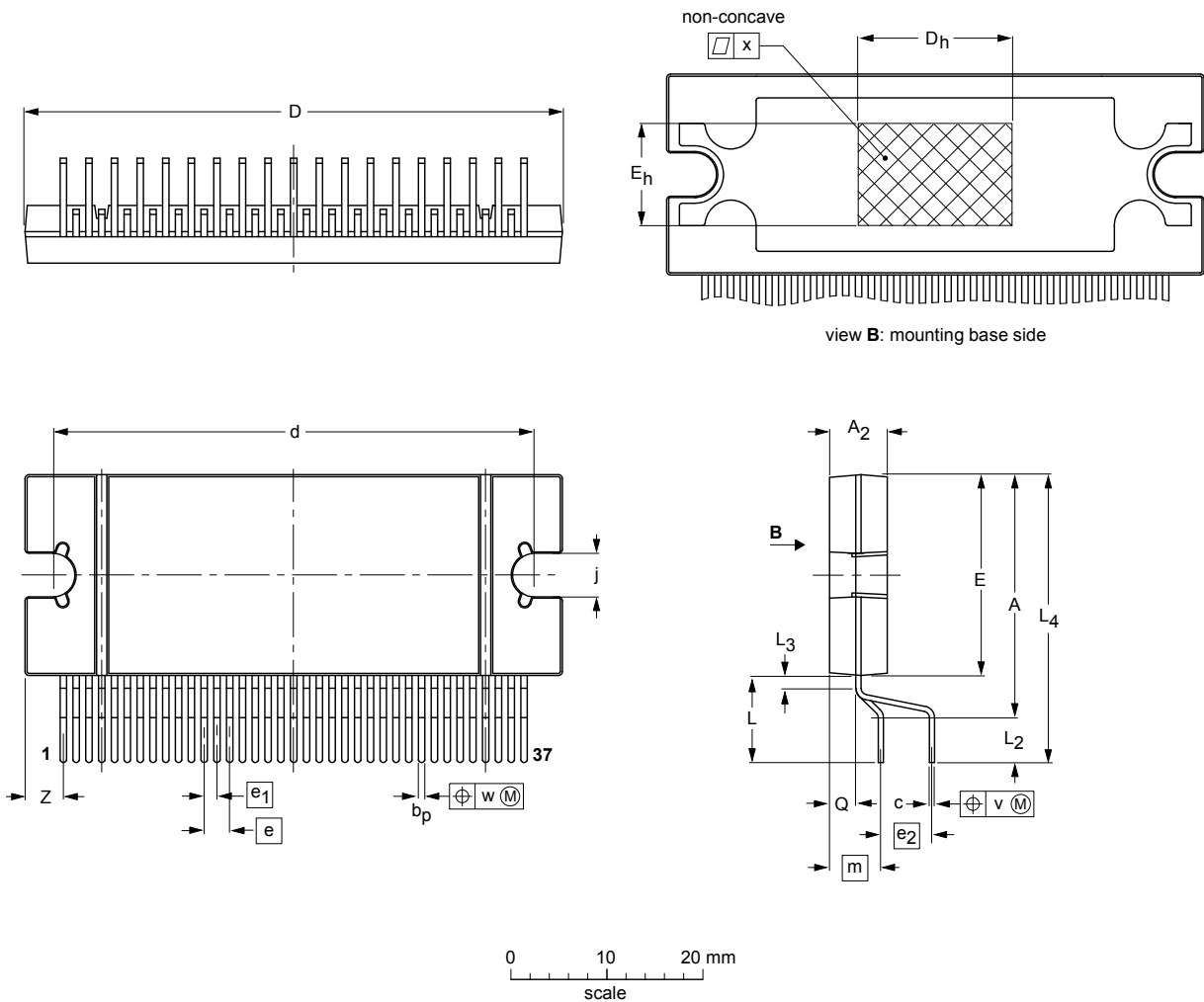
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	41.7	-	42	42.2	mm
E	package width	15.5	-	15.7	15.9	mm
A ₂	package height	4.35	-	4.5	4.65	mm
n ₂	actual quantity of termination	-	-	37	-	



2. Package outline

DBS37P: plastic DIL-bent-SIL power package; 37 leads (lead length 6.8 mm)

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DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₂	b _p	c	D ⁽¹⁾	d	D _h	E ⁽¹⁾	e	e ₁	e ₂	E _h	j	L	L ₂	L ₃	L ₄	m	Q	v	w	x	Z ⁽¹⁾
mm	19	4.65	0.60	0.5	42.2	37.8	12	15.9	2	1	4	8	3.4	6.8	3.9	1.15	22.9	4	2.1	0.6	0.25	0.03	3.30
		4.35	0.45	0.3	41.7	37.4		15.5					3.1	3.1	0.85	22.1		1.8					2.65

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT725-1	---	---	---			01-11-14 02-11-22

Fig. 1. Package outline DBS37P (SOT725-1)

3. Legal information

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